

# Architectural Implications of Brick and Mortar Silicon Manufacturing

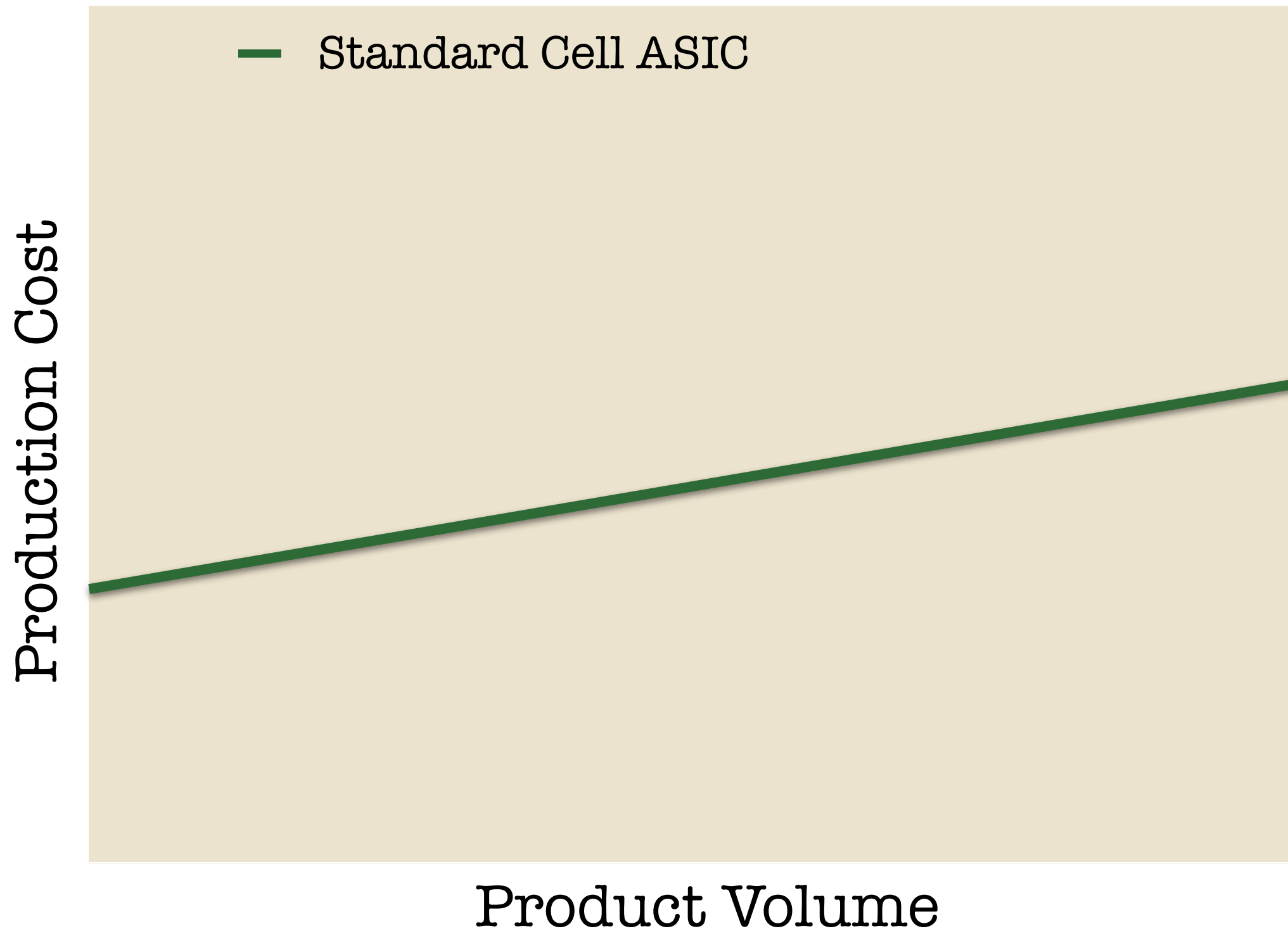
Martha Mercaldi Kim  
Mark Oskin

University of Washington

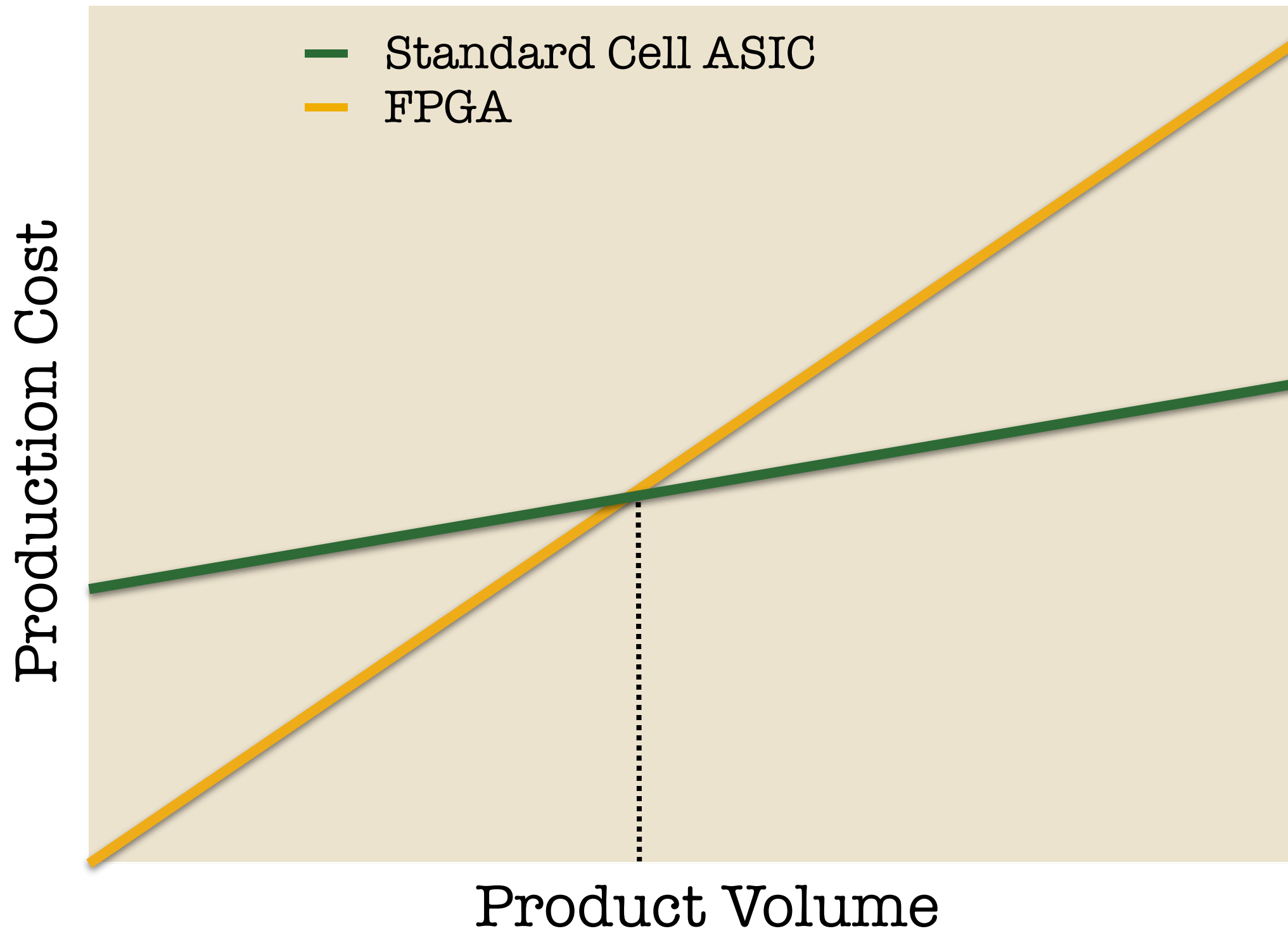
Mojtaba Mehrara  
Todd Austin

University of Michigan

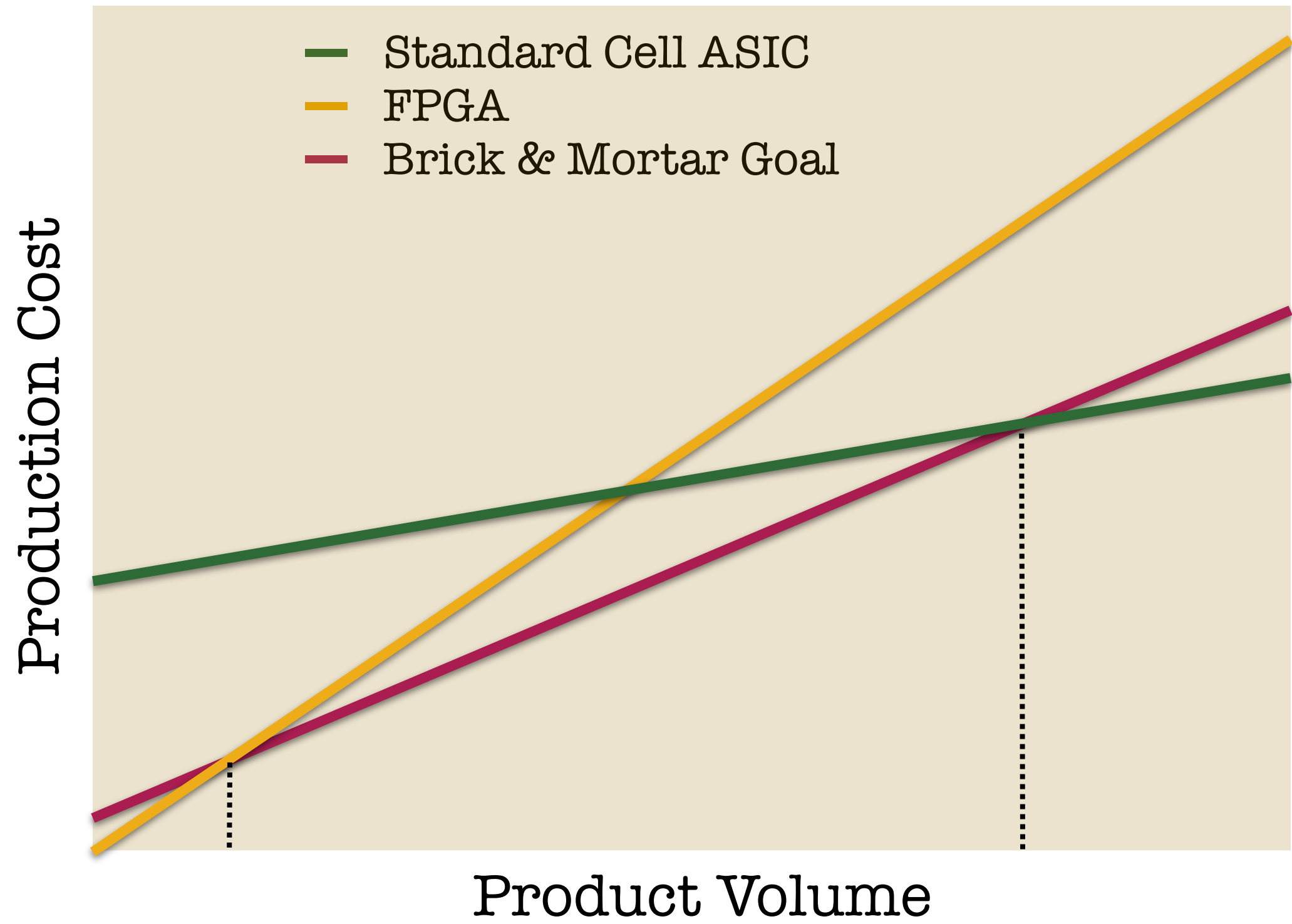
# Cost of Production



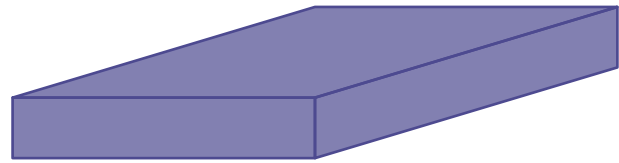
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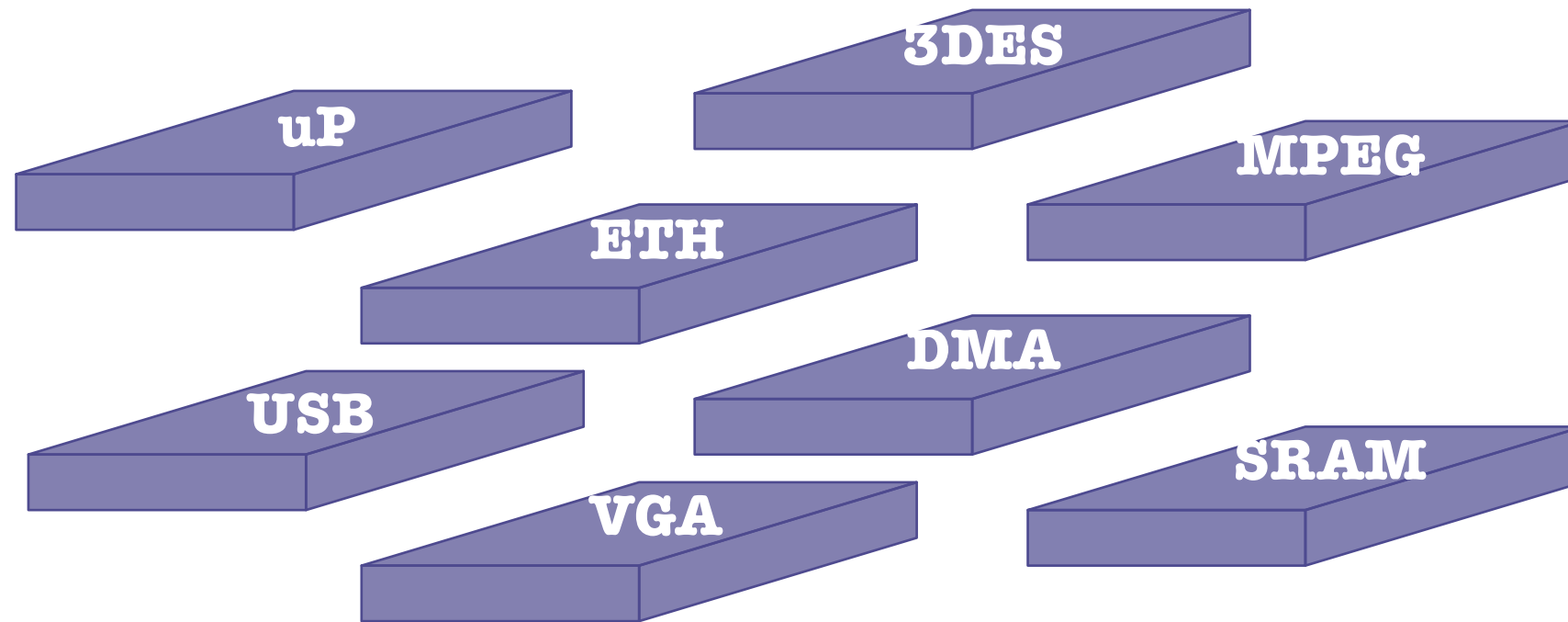
# Brick and Mortar Chips



## 1. Bricks

- Mass-produced ASICs
- Standard interface
- Fixed set of functions

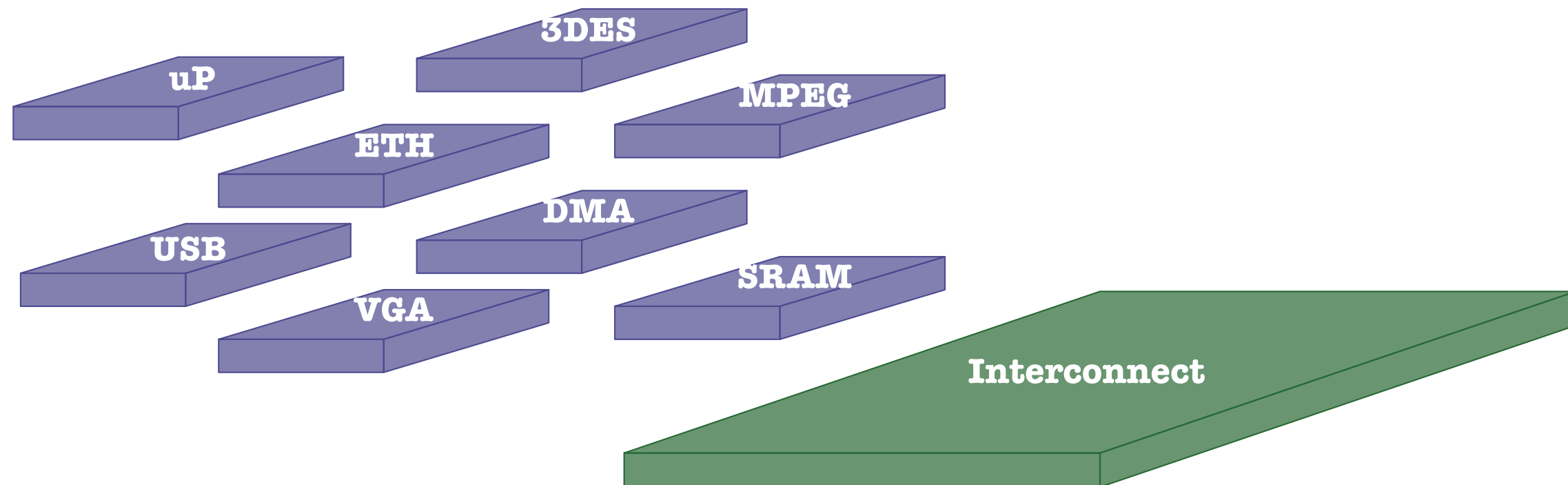
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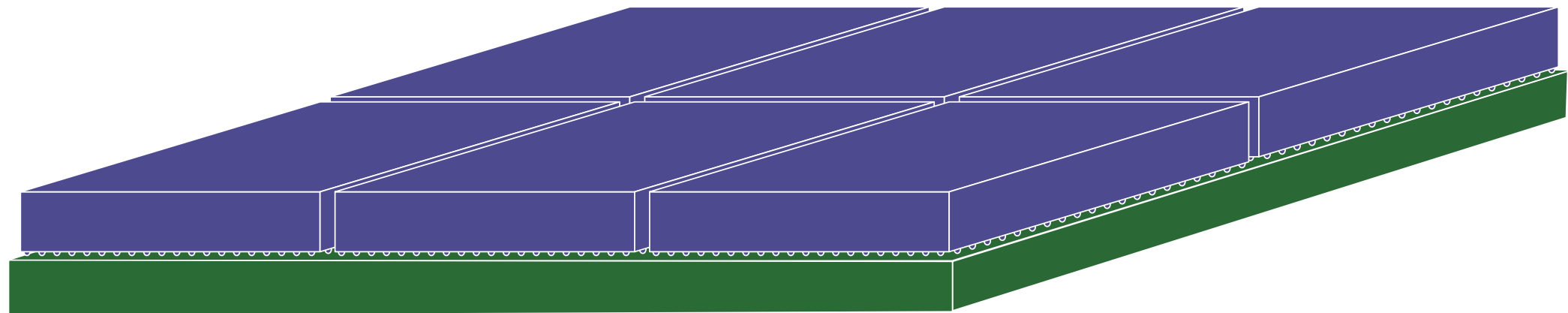
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- Mass-produced ASIC
- Standard interface
- Single, interconnect function

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## 3. Assembly

- Alignment
  - e.g. robotics, fluidic
- Bonding
  - e.g. flip-chip, proximity



# Benefits of Brick and Mortar

- **Chip manufacture:** mask-free, fab-free, improved yields
- **Chip performance:** mostly ASIC
- **Chip design:** uses today's SoC design flow

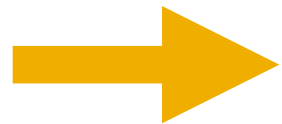
# Why Should Architects Care?

- Good architecture essential for viability
  - Brick function and form-factor
  - Inter-brick interconnect design

# Outline

- Brick and Mortar Chips

- Definition
- Potential
- Architectural Questions



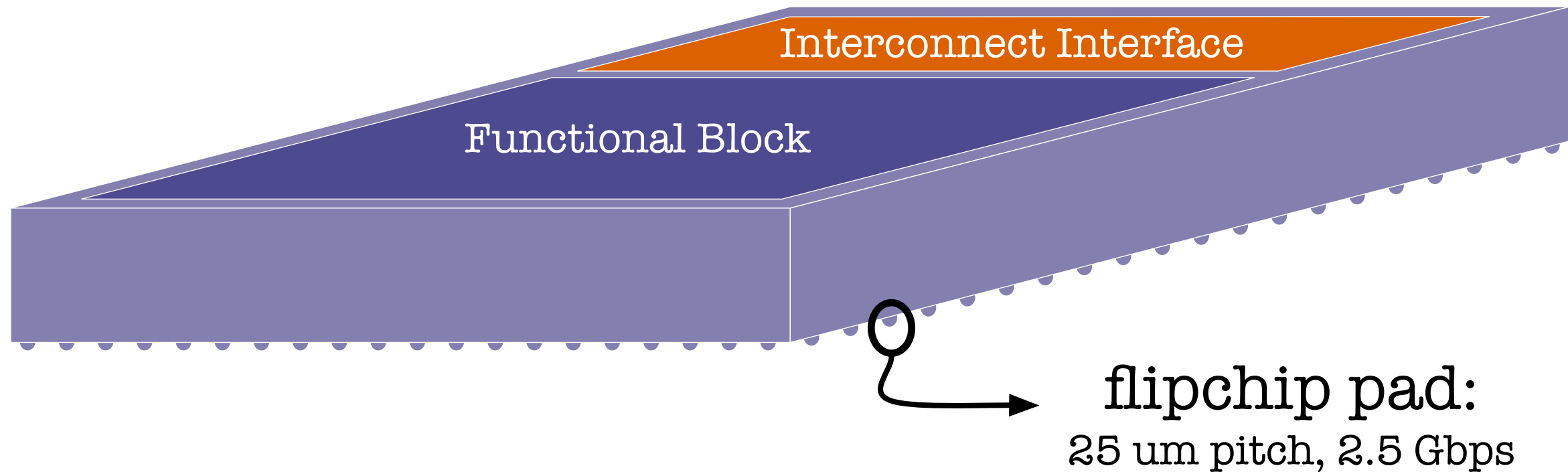
- Brick and Mortar Architecture

- Bricks
- Interconnect

- Brick and Mortar Assembly

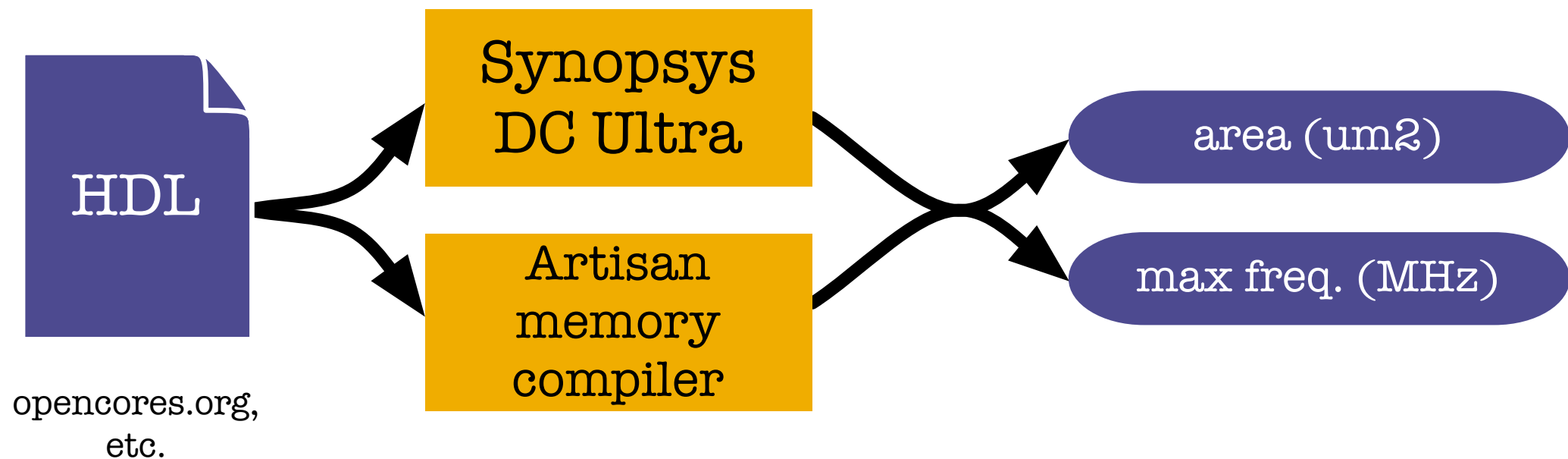
- Options
- Interaction with architecture

# Brick Form Factor



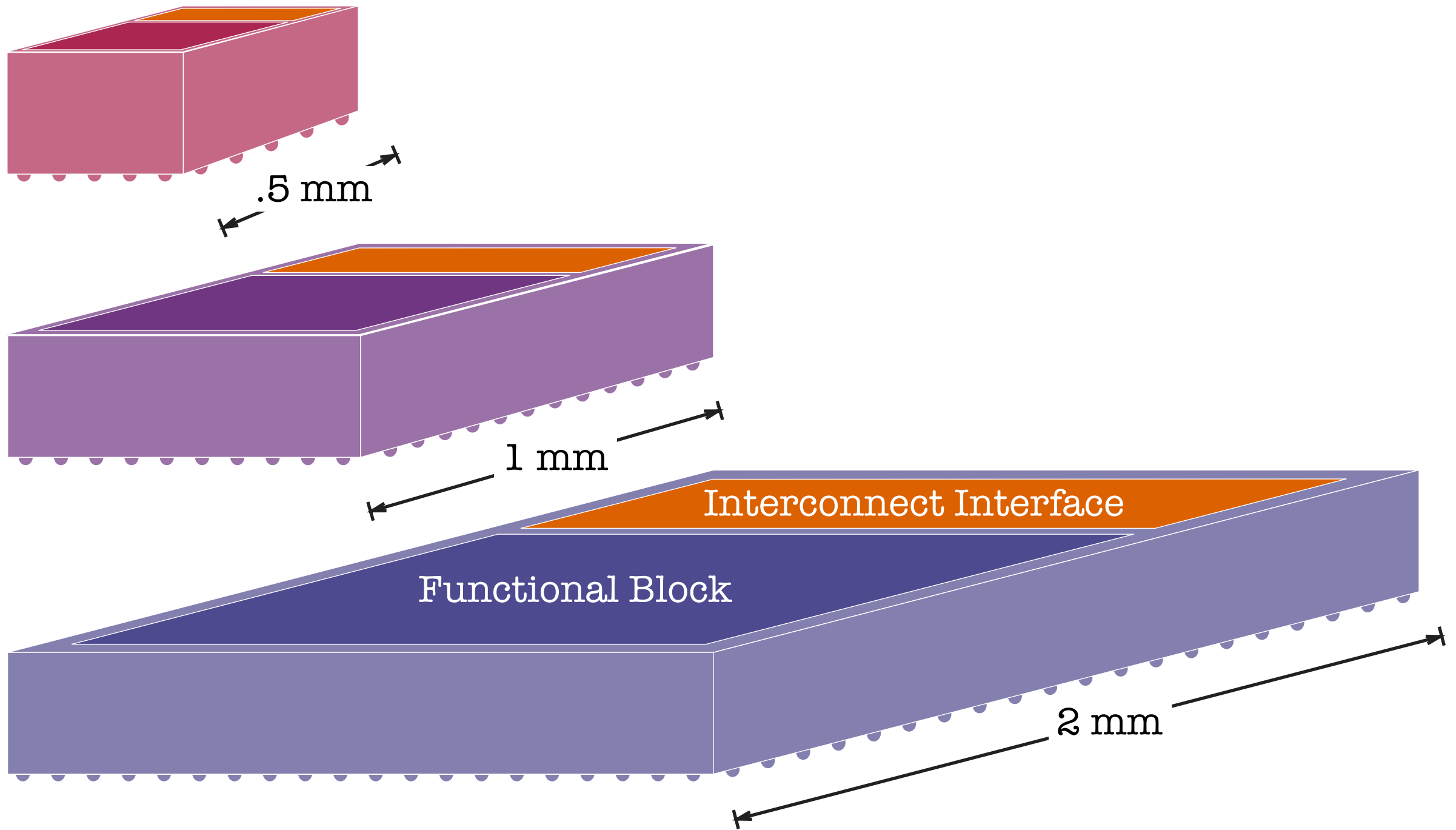
- Each brick . . .
  - is square
  - has 15% of area reserved for extra circuitry
  - has one surface covered with flipchip pads

# Brick Architecture



Function Description	Area (um <sup>2</sup> )	Max Freq. (MHz)
USB 1.1 Physical Layer	2,201	2941
JPEG Decoder	625,457	629
RISC Core + 256K Cache	3,111,025	1087

# Multiple Brick Sizes



# Brick Size Selection

Function Description	Circuit		Freq. Range at Brick Size		
	Area (um <sup>2</sup> )	Max Freq. (MHz)	Small	Medium	Large
256 K SRAM (single-ported)	2,729,344	2315	No Space	No Space	N/A - 2315
JPEG Decoder	625,457	629	No Space	N/A - 629	No Benefit
VGA/LCD Controller	4,301	1219	N/A - 1046	N/A - 1219	No Benefit

- Smallest brick to fit circuit, unless bandwidth **severely** constrained

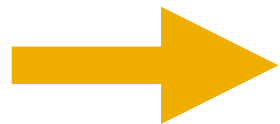
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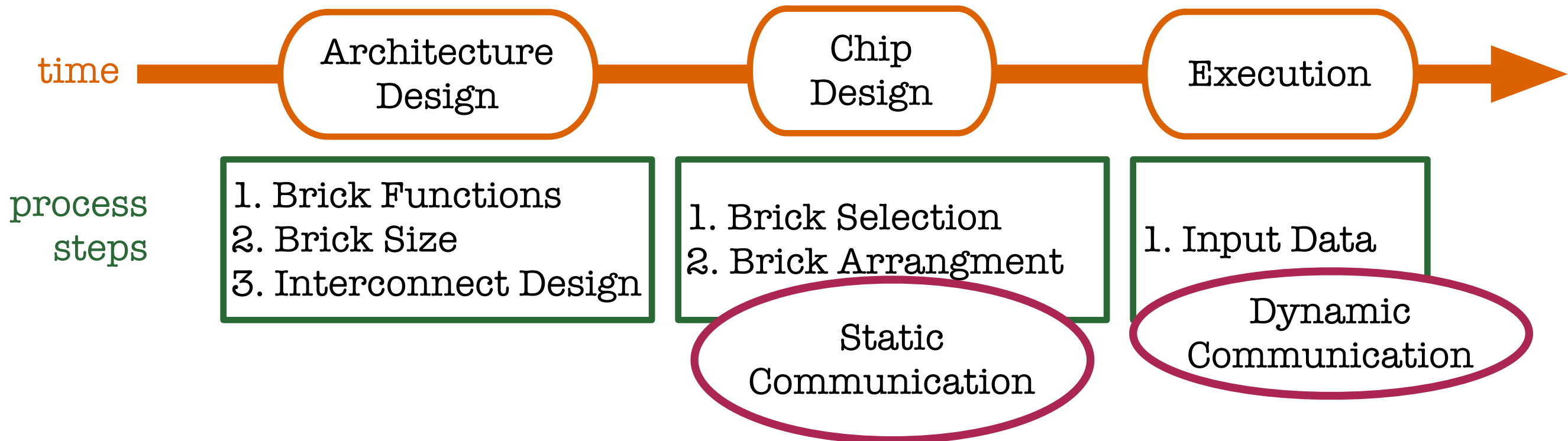


- Brick and Mortar Assembly

- Options
- Interaction with architecture



# Interconnect Dilemma



- General purpose interconnect facilities
  - Communication known at design time → configurable wires
  - Dynamic communication → packet-switched net

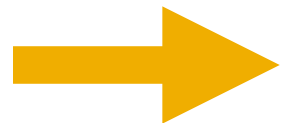
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- Brick and Mortar Architecture

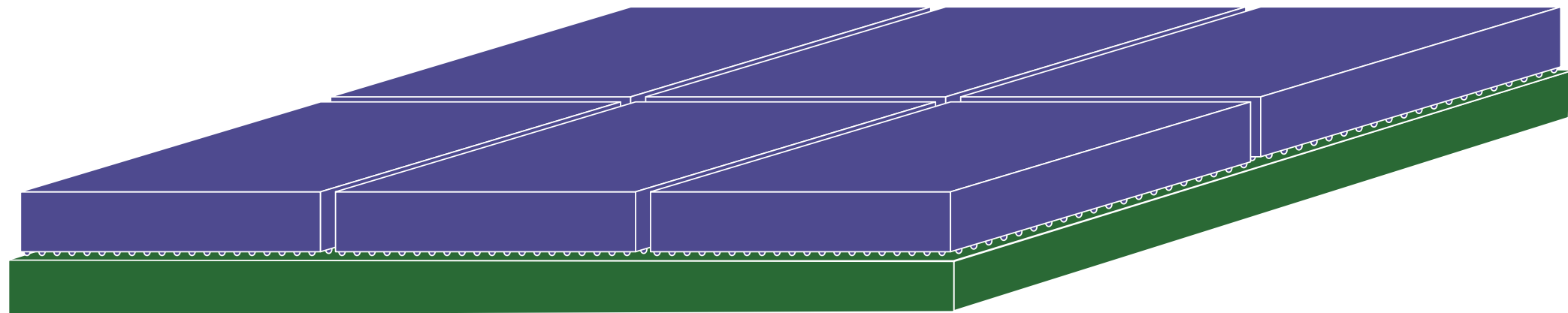
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# Assembly Alternatives

- Alignment
  - Robotic
  - Self-Assembly
  - Martha + tweezers
  - ...
- Bonding
  - Flip-chip
  - Proximity
  - ...

# Assembly Alternatives

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- Robotic \$\$\$, but fast
- Self-Assembly \$, but slow
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- Bonding

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- Flip-chip medium-density, but more robust connection

- Proximity high-density

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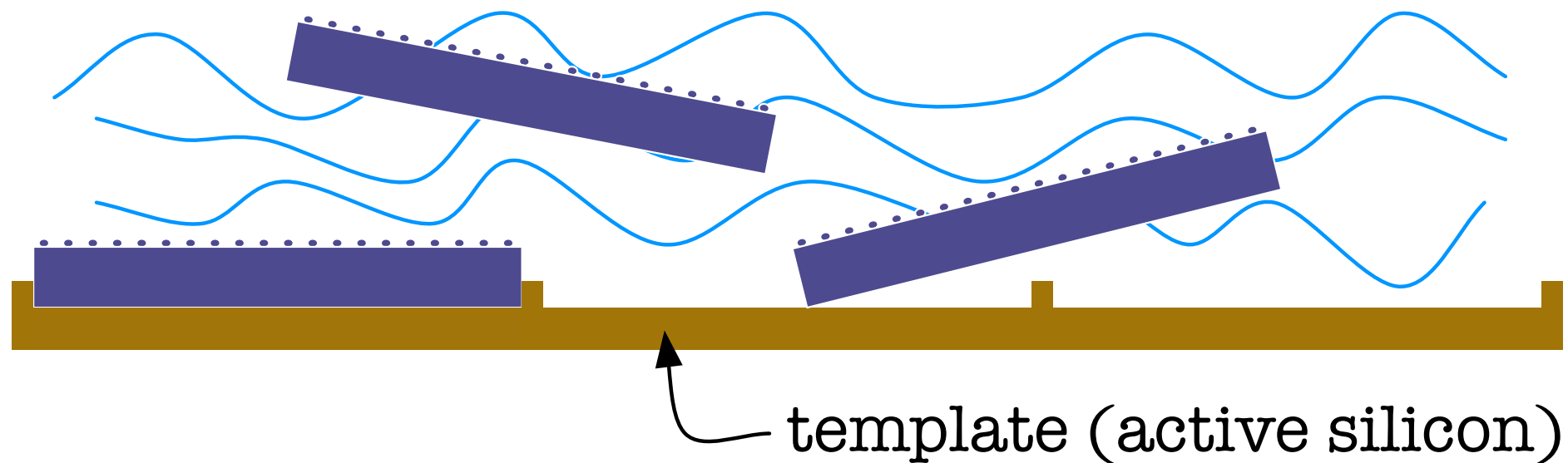
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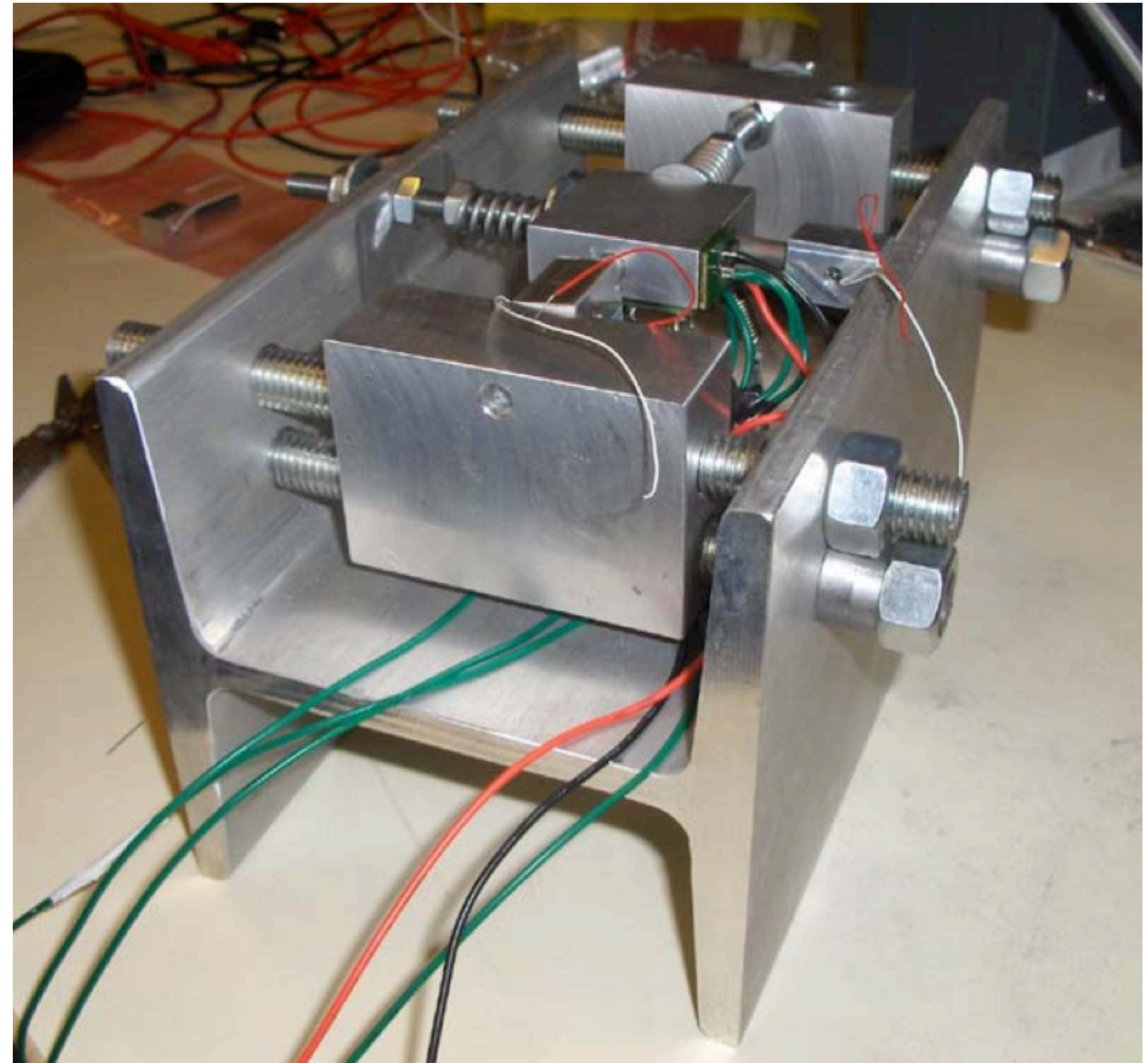
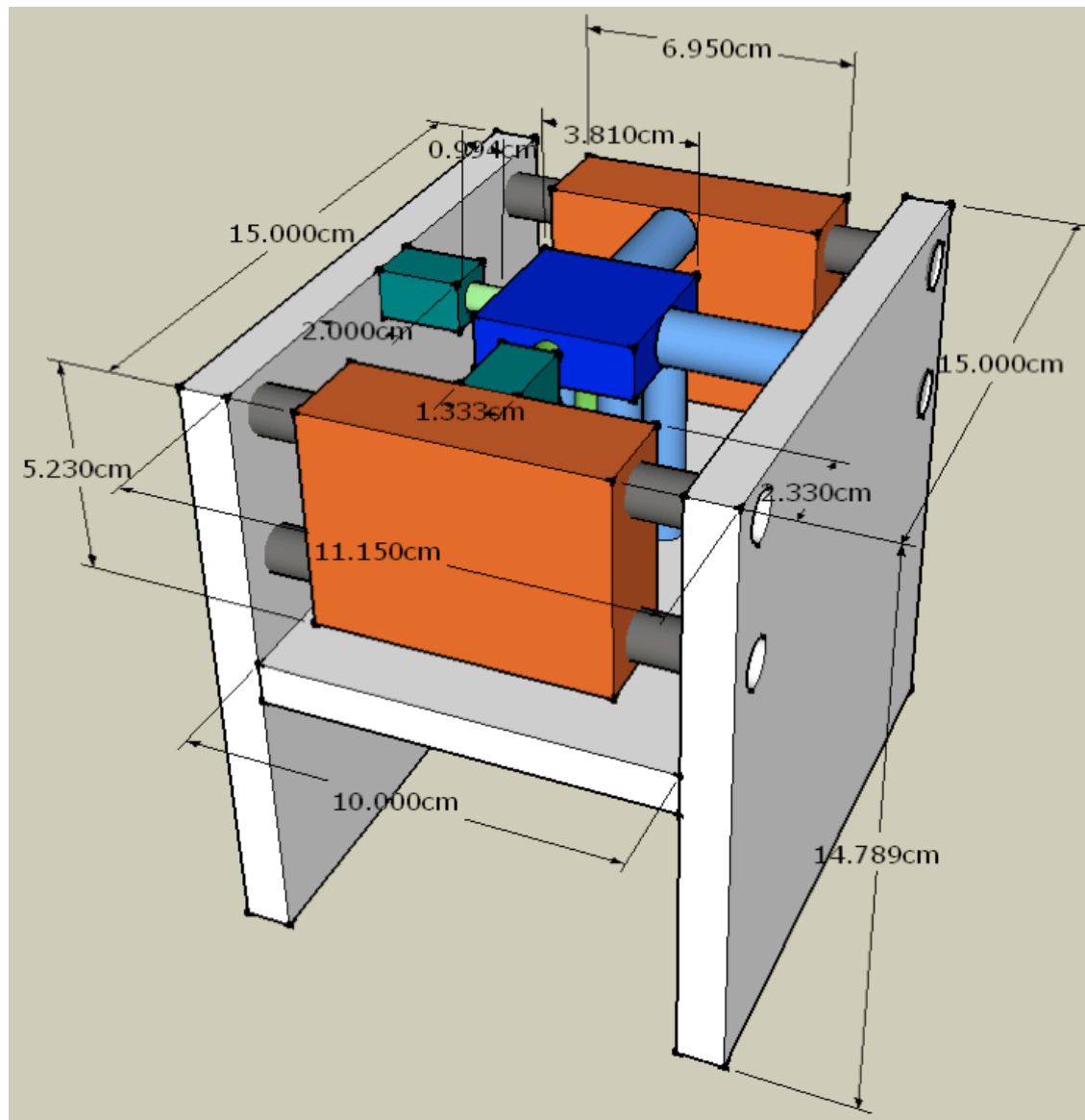


# Alignment: Fluidic Self Assembly



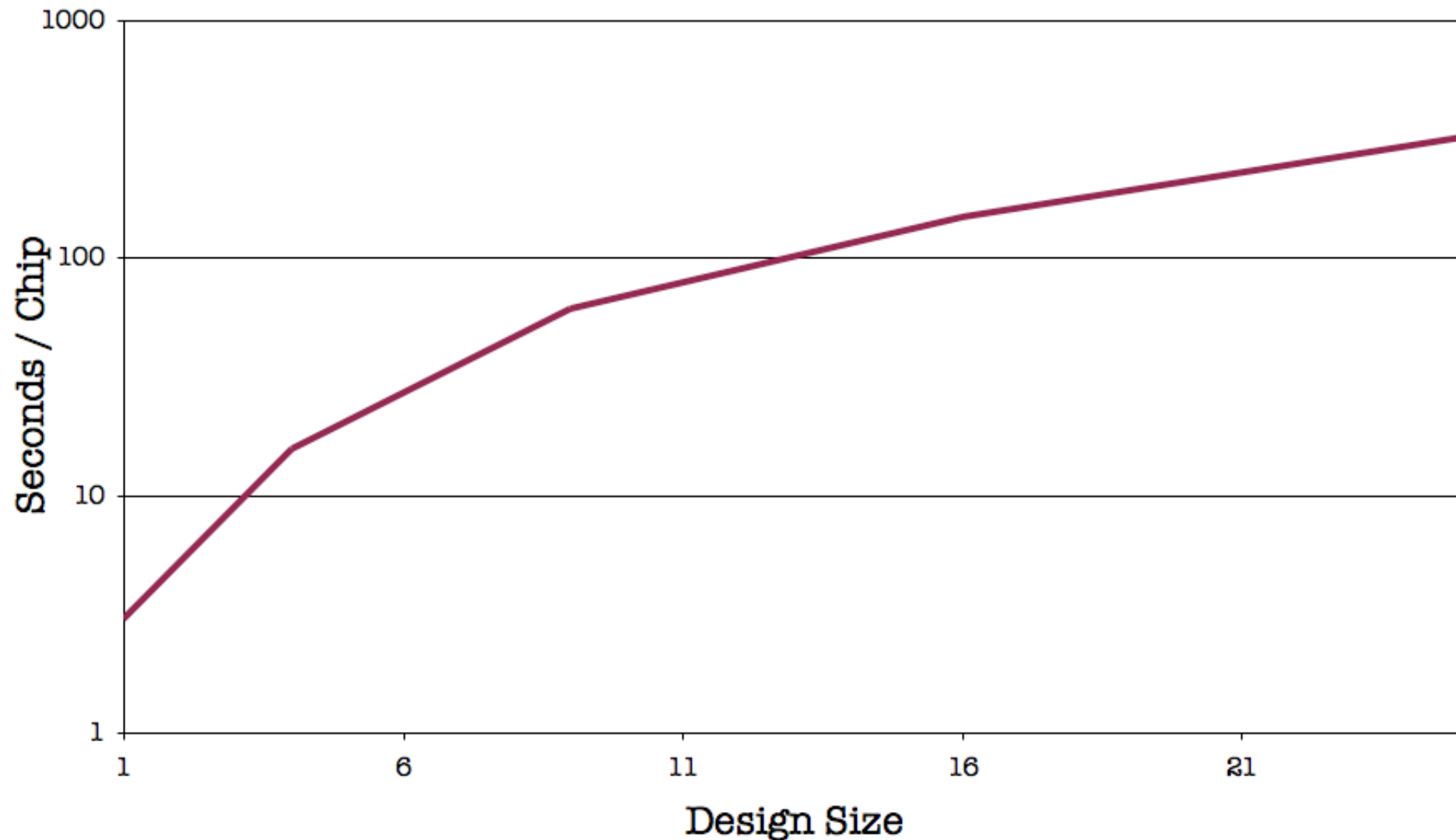
- Template - brick communication via proximity communication
  - Brick type check, BIST, speed grade
- Polymer on template can grip or eject bricks

# Alignment: Fluidic Self Assembly



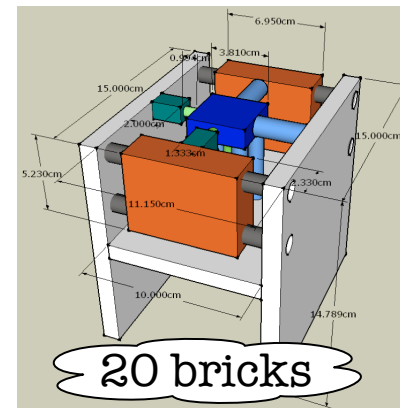
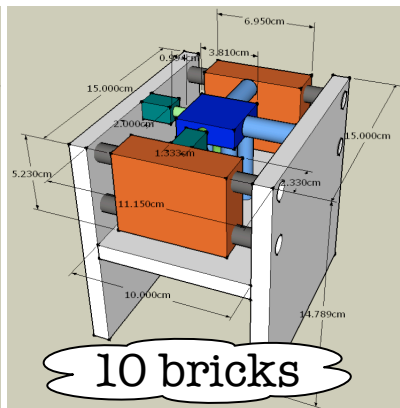
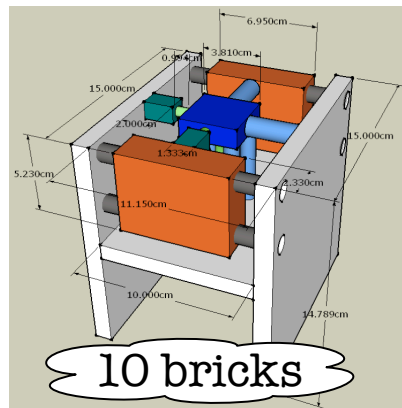
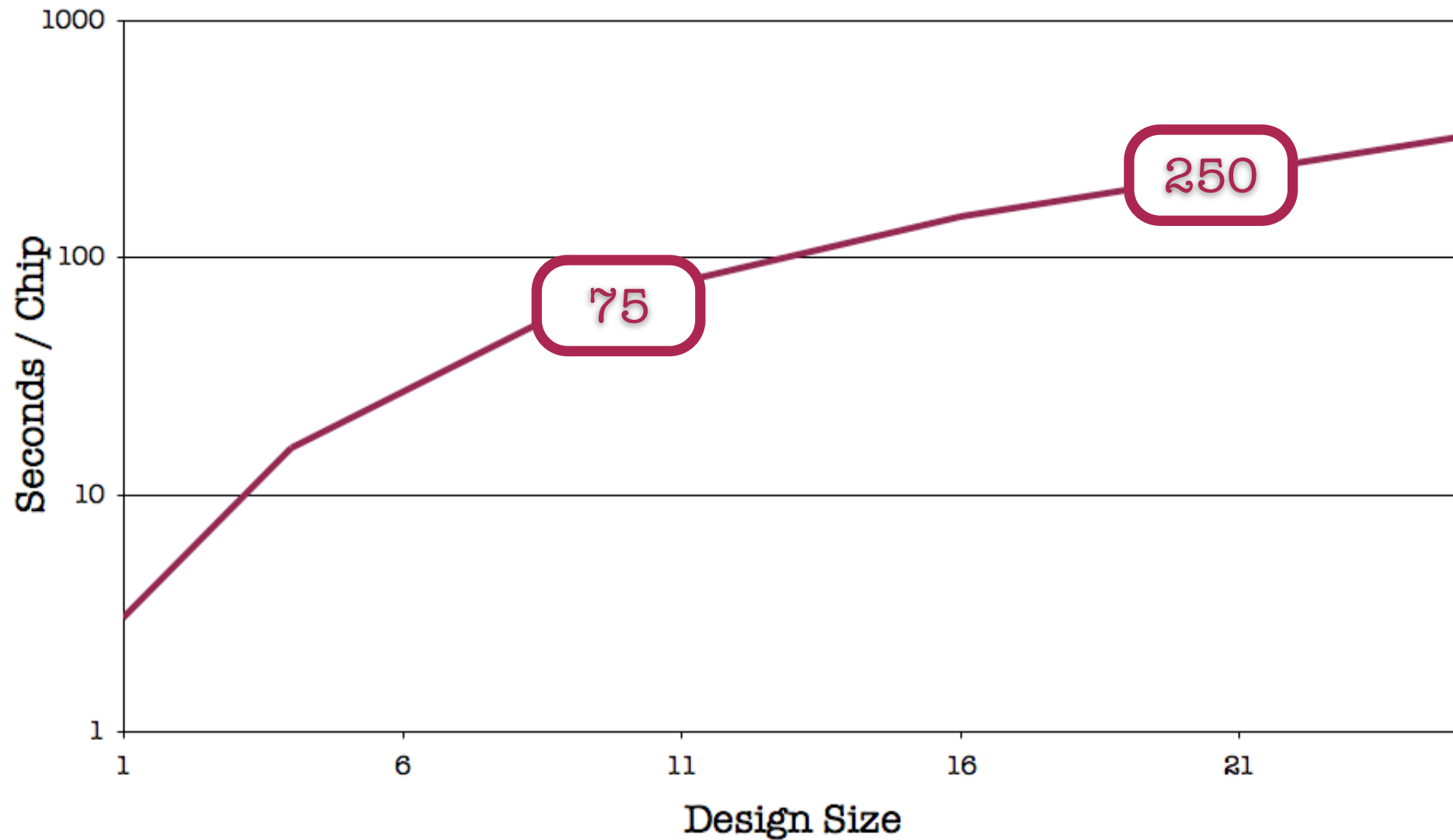
- Washington EE experimental system

# Assembly Time v. Number of Bricks

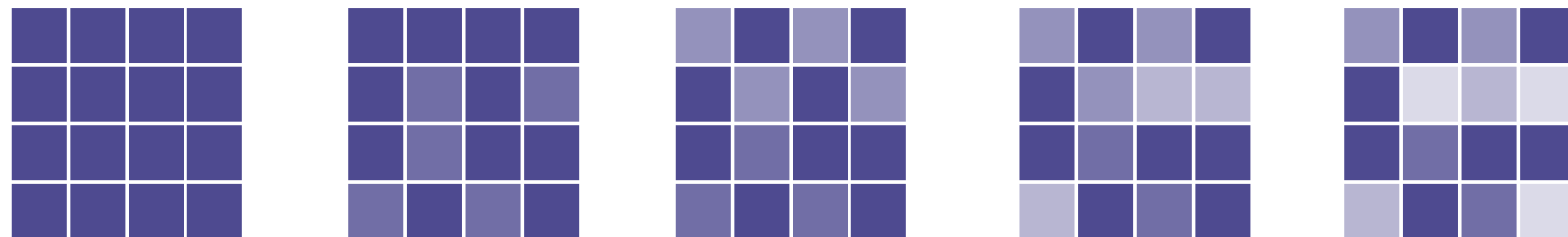
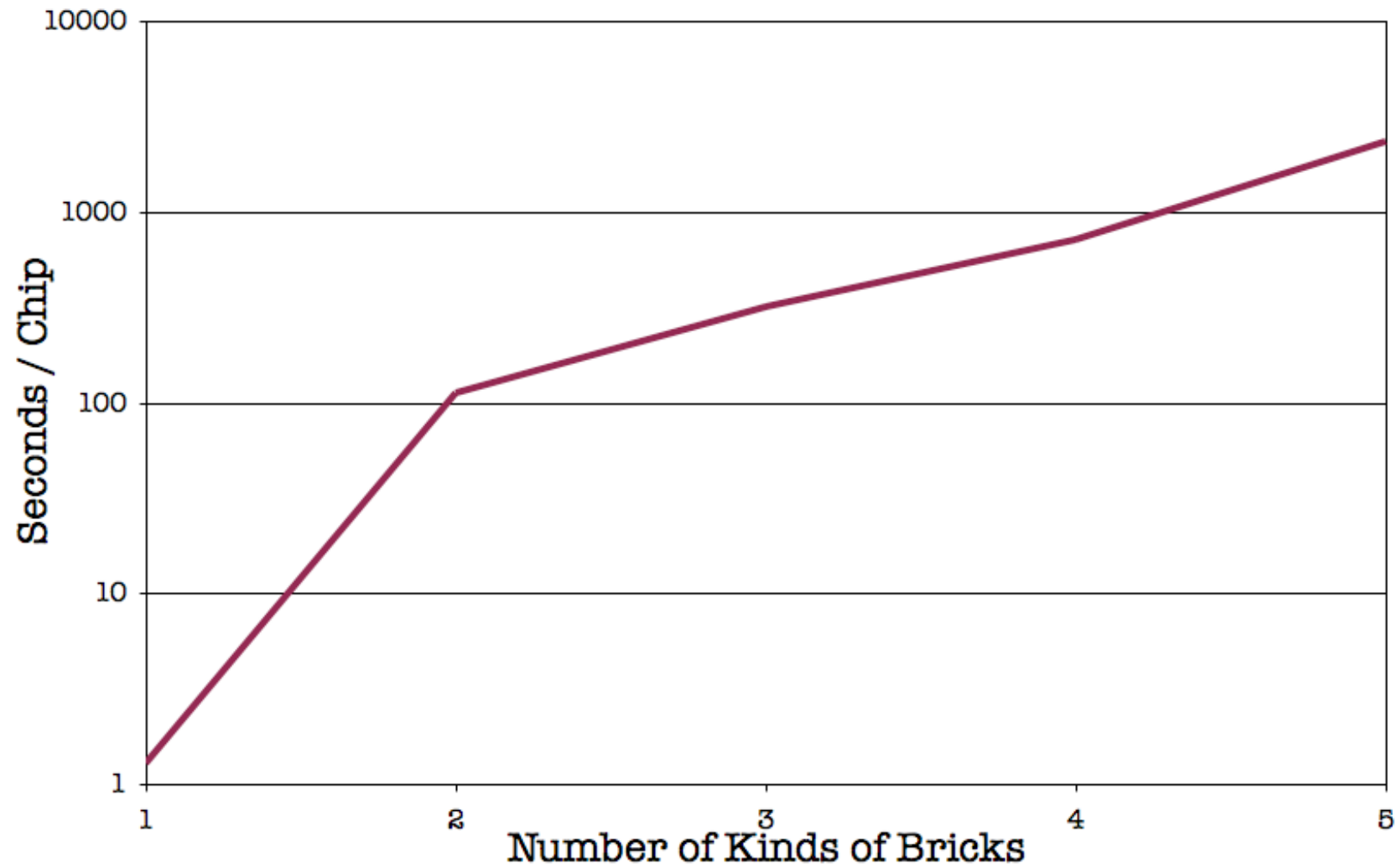


- Statistical simulator driven by experimentally derived rates of assembly and disassembly

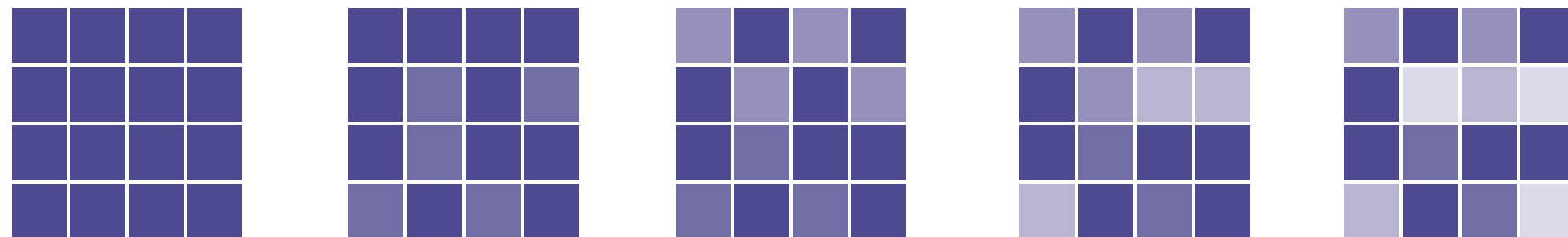
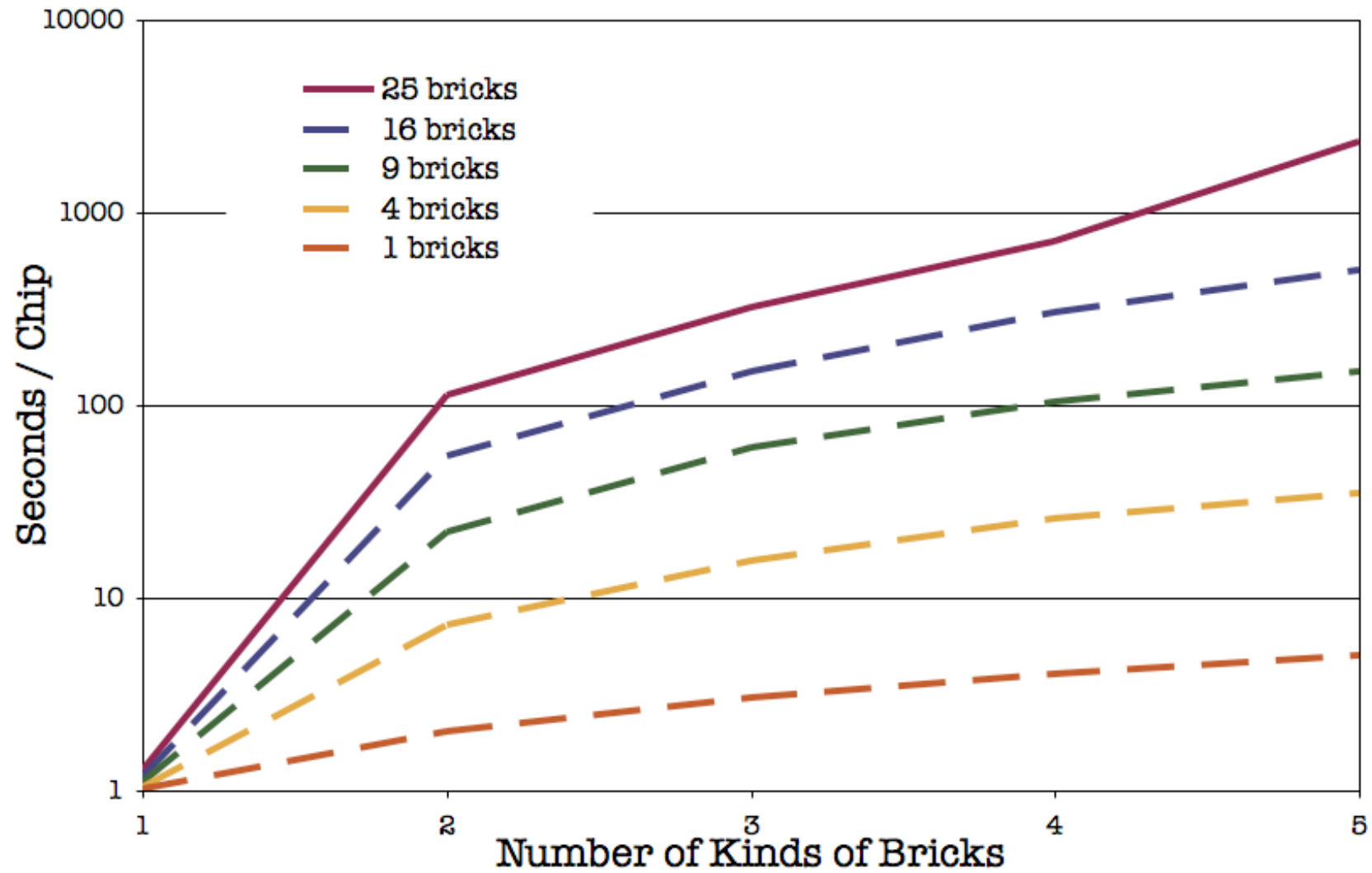
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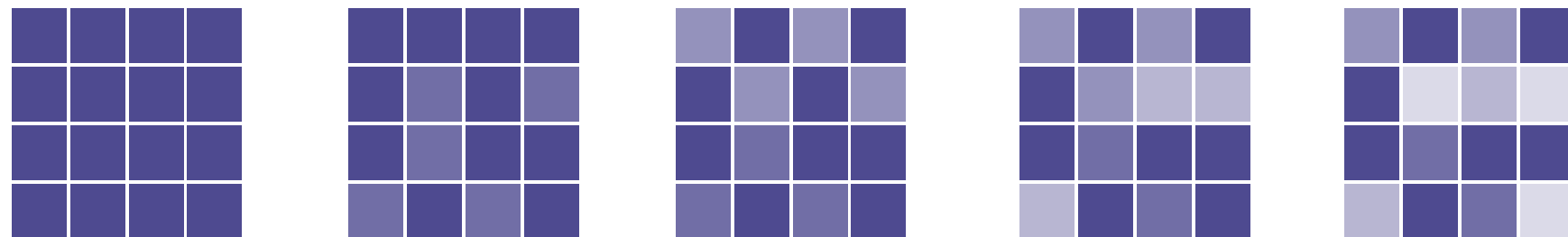
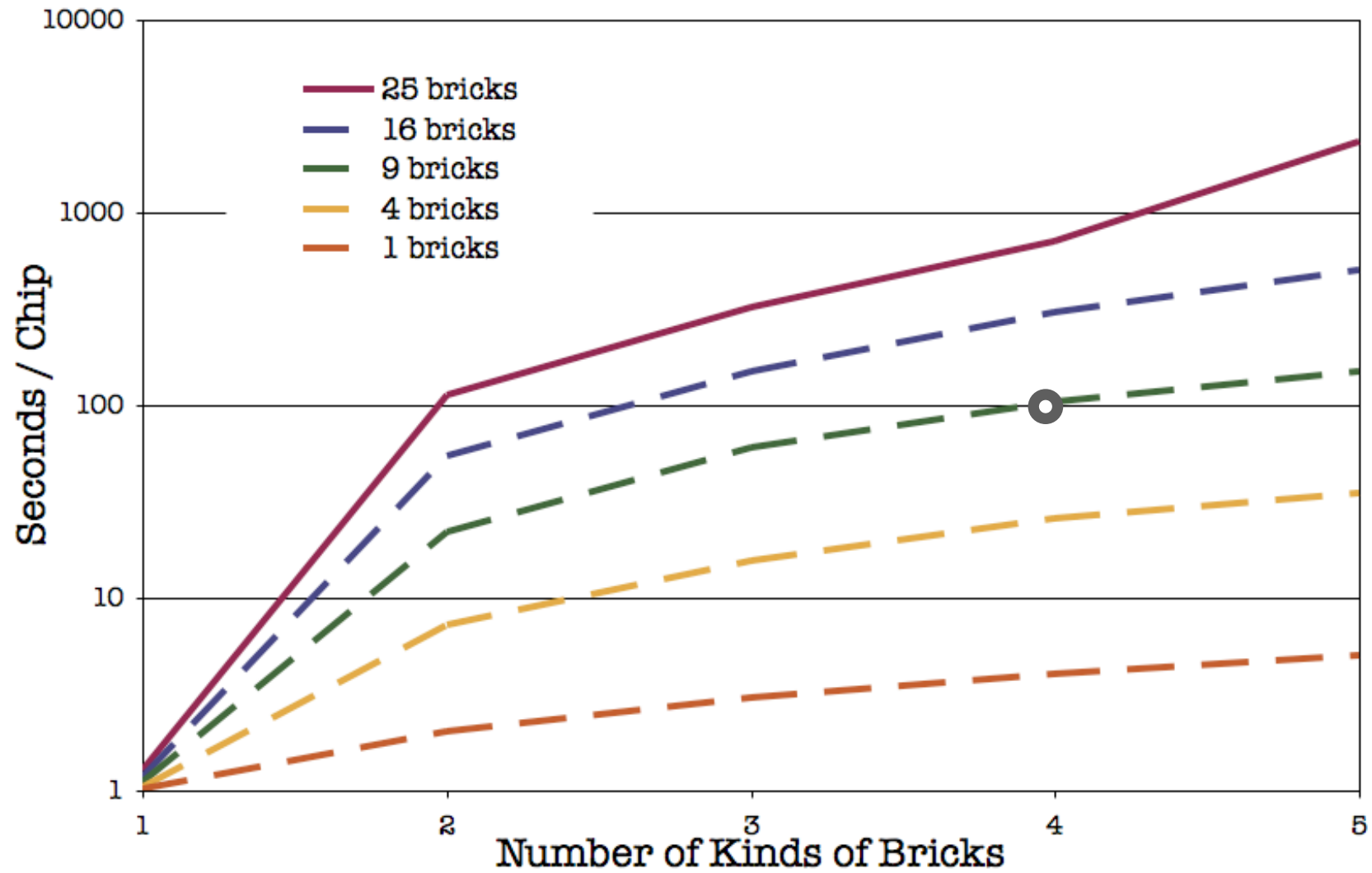
# Assembly Time v. Kinds of Bricks



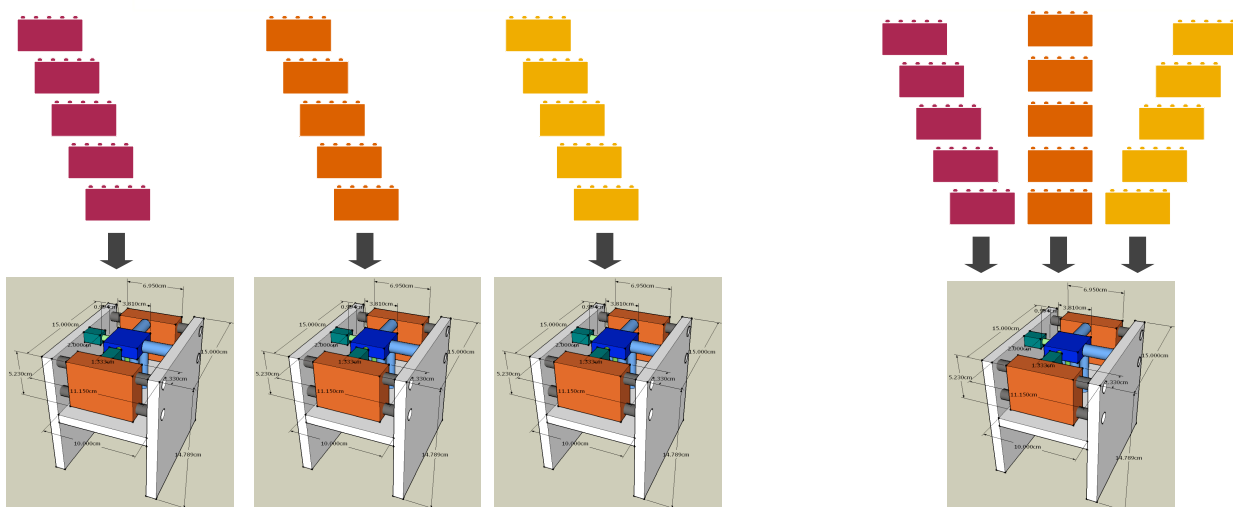
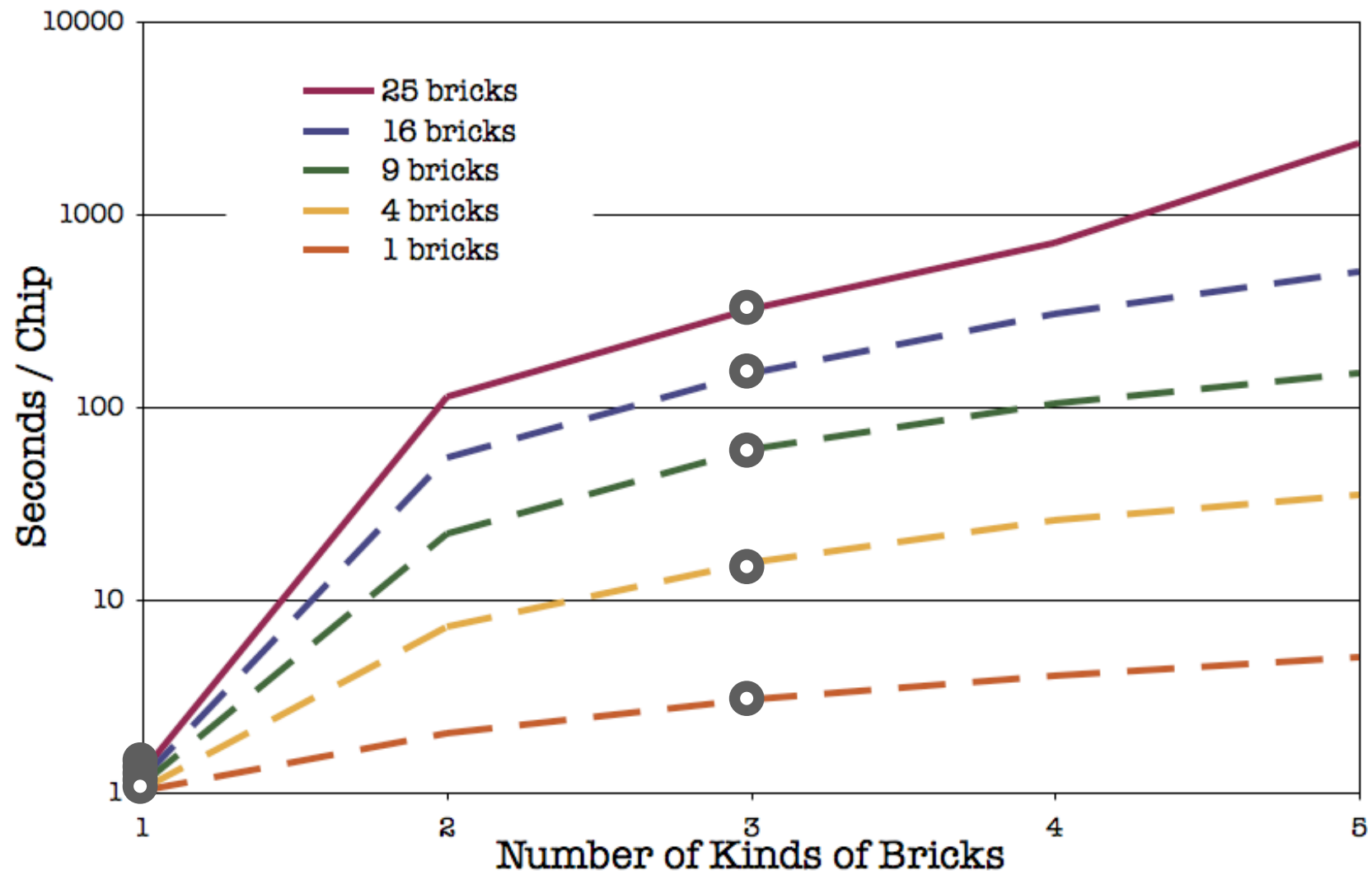
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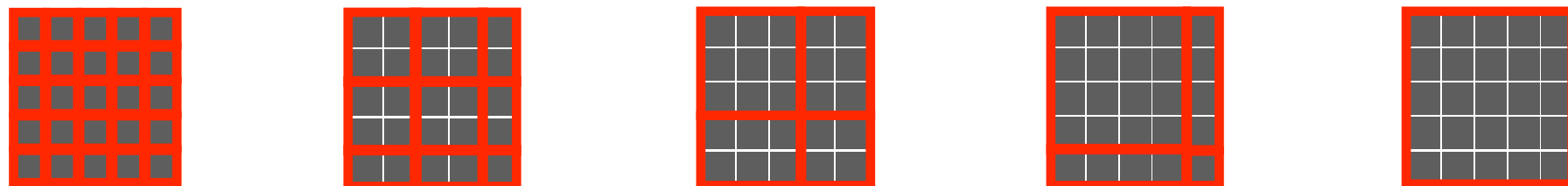
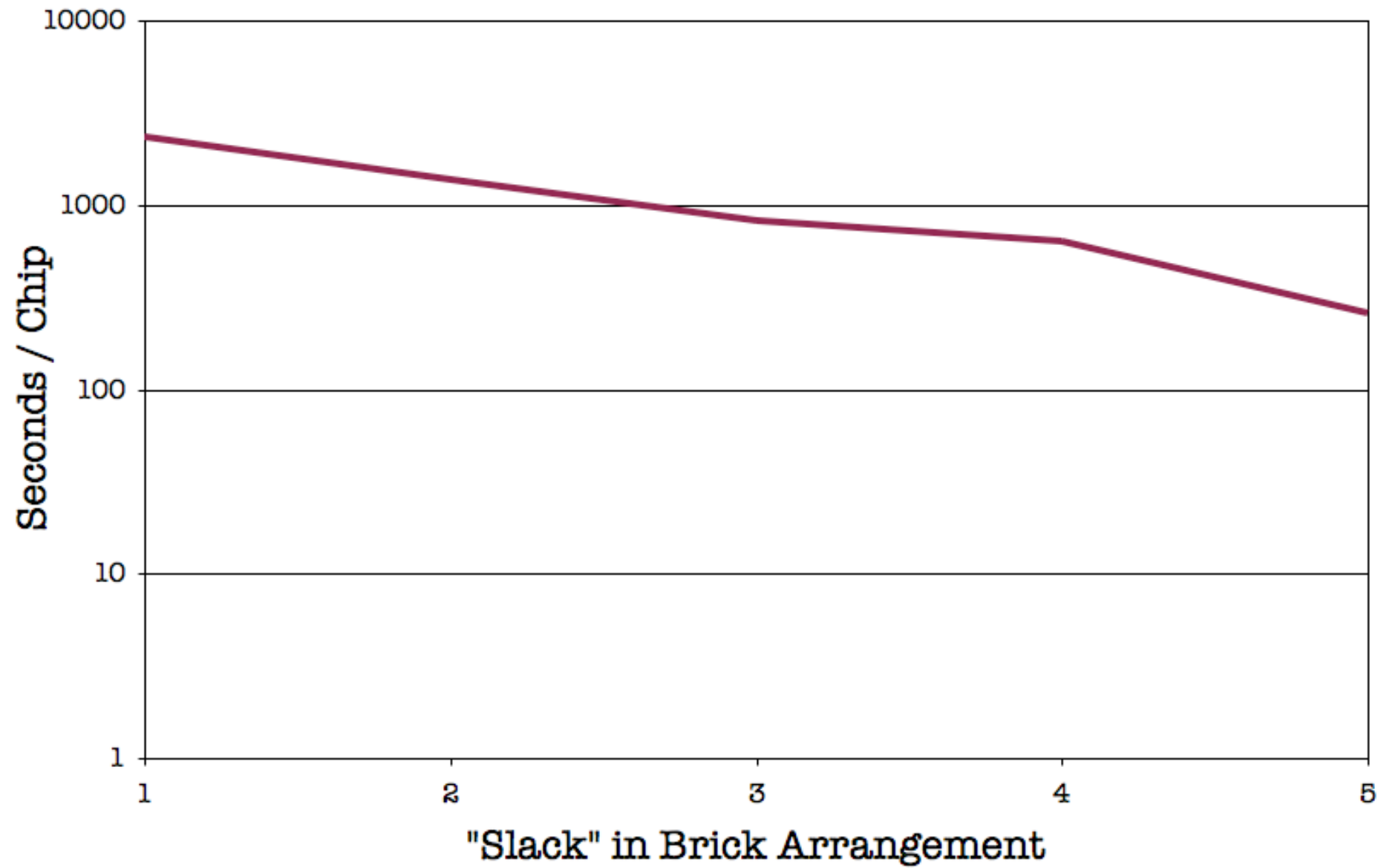


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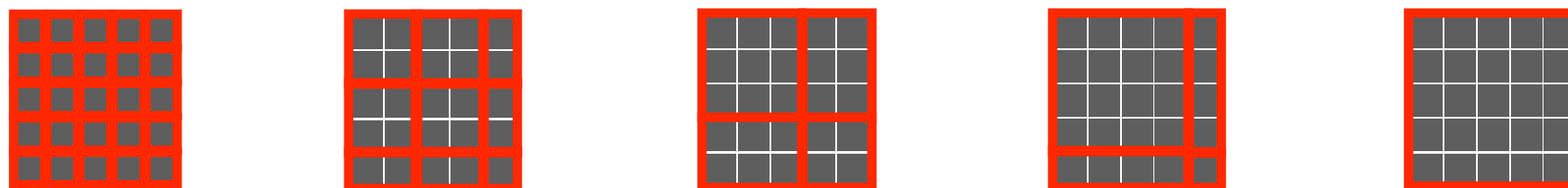
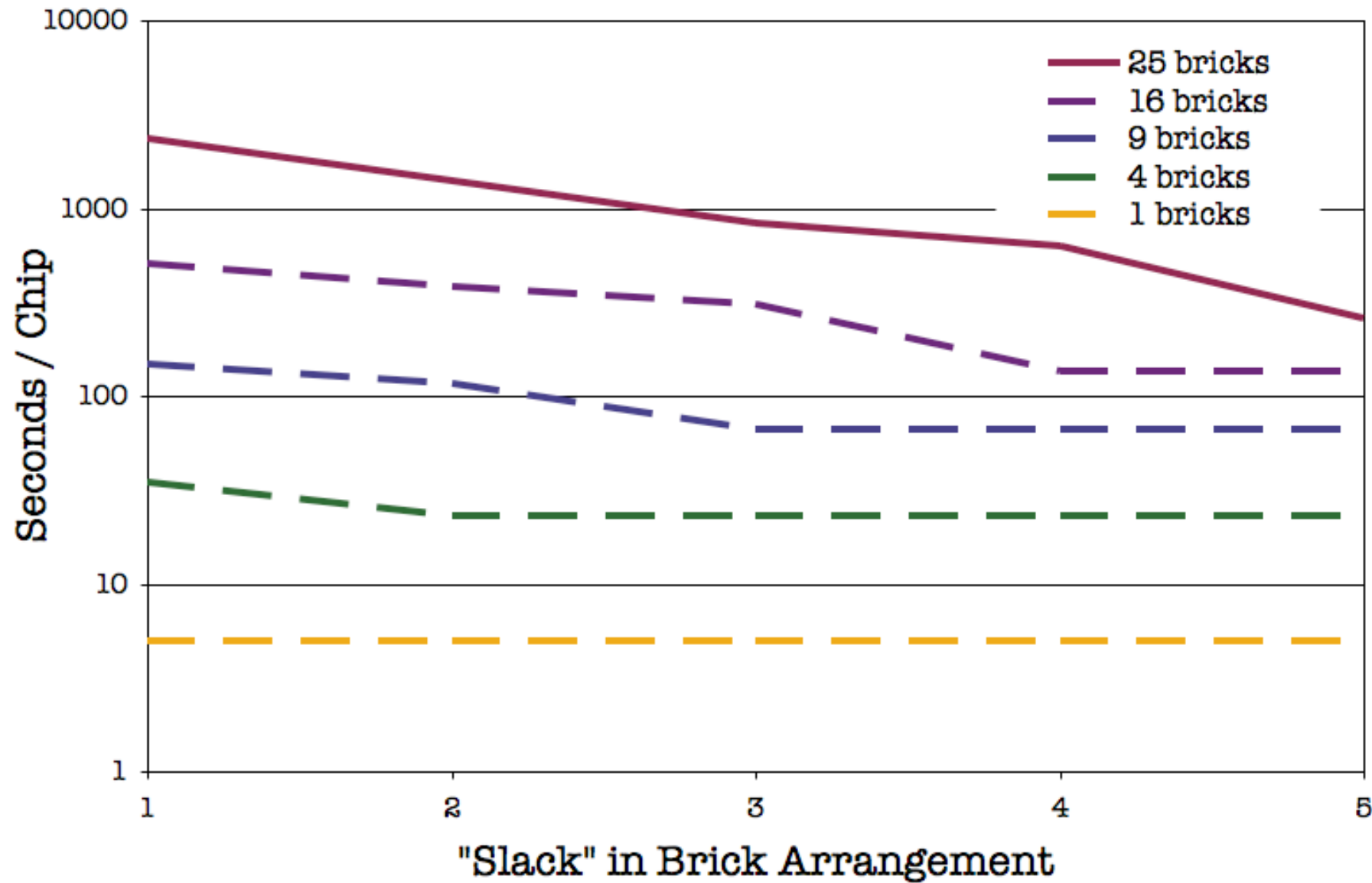




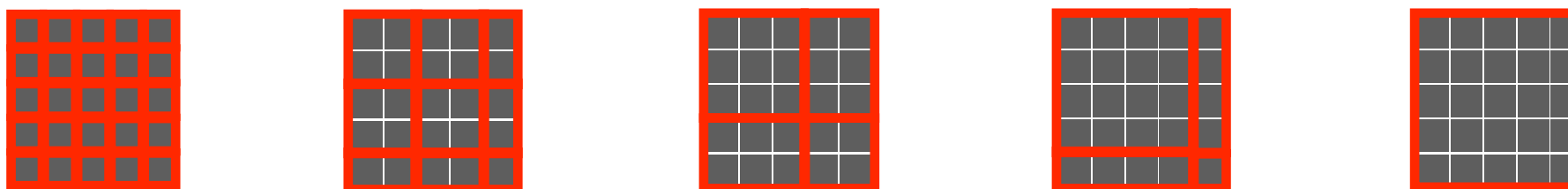
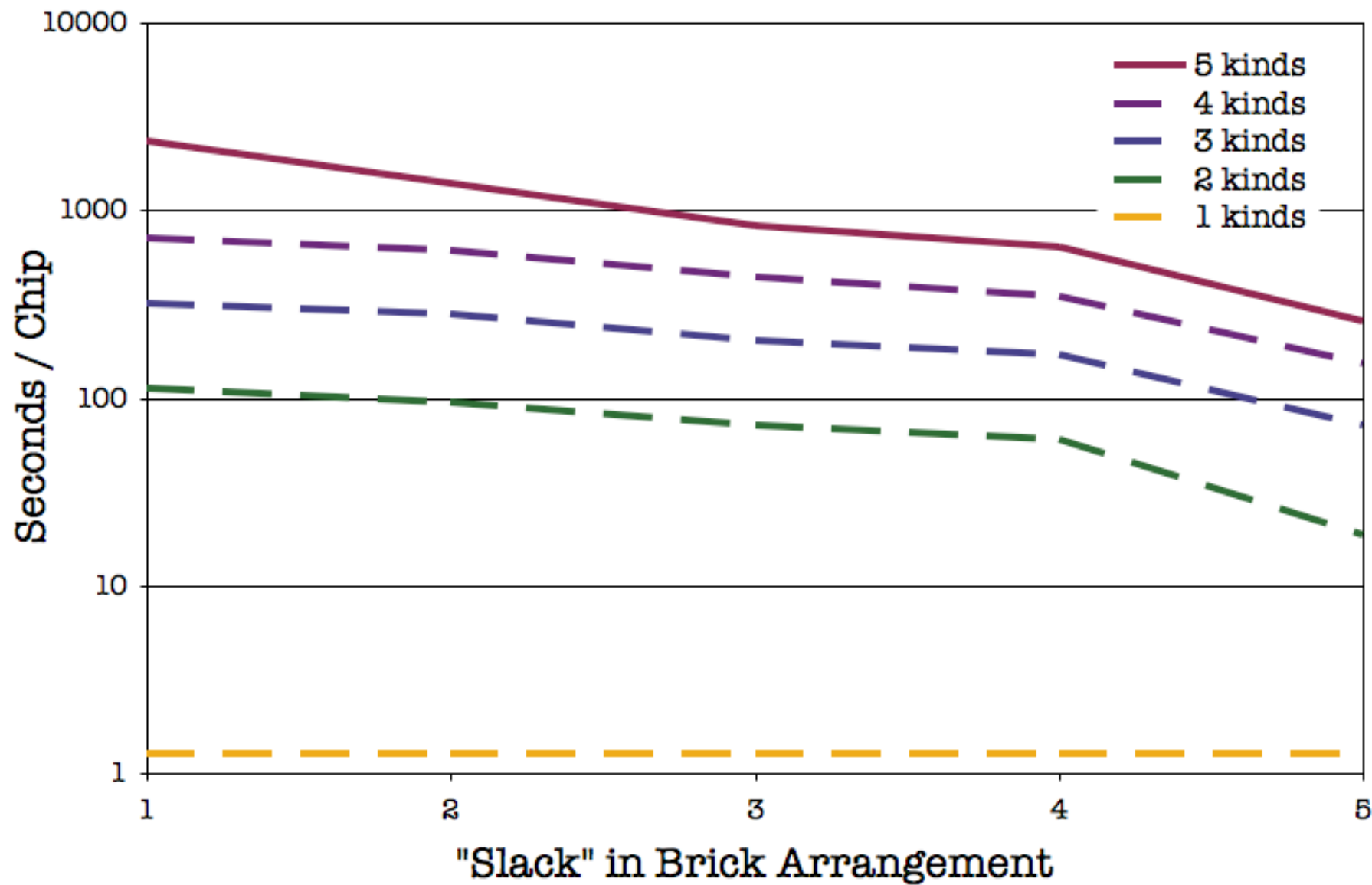
# Assembly Time v. Brick Arrangement Slack



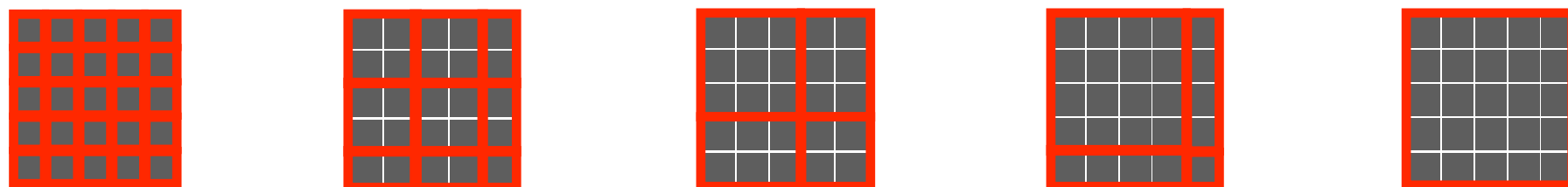
# Evaluating Slack: Design Size



# Evaluating Slack: Brick Kinds



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# Assembly and Architecture

- Architecture can assist assembly by
  - Reducing the number of kinds of bricks
    - i.e., two brick kinds v. one slightly reconfigurable circuit
  - Accommodating variable assemblies

# Conclusion

Brick and Mortar process offers ASIC-like chips without the masks and fabs

Architecture is crucial to meet the performance goals of the process

With low-cost assembly techniques, can meet the economic goal as well